Panel Fan-Out Manufacturing
Why, When, and How?

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Environment

• We all can agree that ….
  – Packaging is driving increased system performance and value.
  – Fan-out is blurring of the lines between silicon and package.
  – Question for tonight… WILL IT STOP AT WAFER LEVEL?

• Why will Panel disrupt the electronics Industry?
  – Cost, new functionality, or reliability

• When will this disruption occur?
  – Now, 2 to 5 years, or never

• How will this disruption materialize?
  – Scaling up from wafer level process or new technology